

# SOT418-4

plastic, heatsink small outline package; 20 leads; low stand-off height

8 February 2016

Package information

## 1. Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP20
Package type industry code	HSOP20
Package style descriptive code	HSOP (heatsink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	10-3-2005

Table 1. Package summary

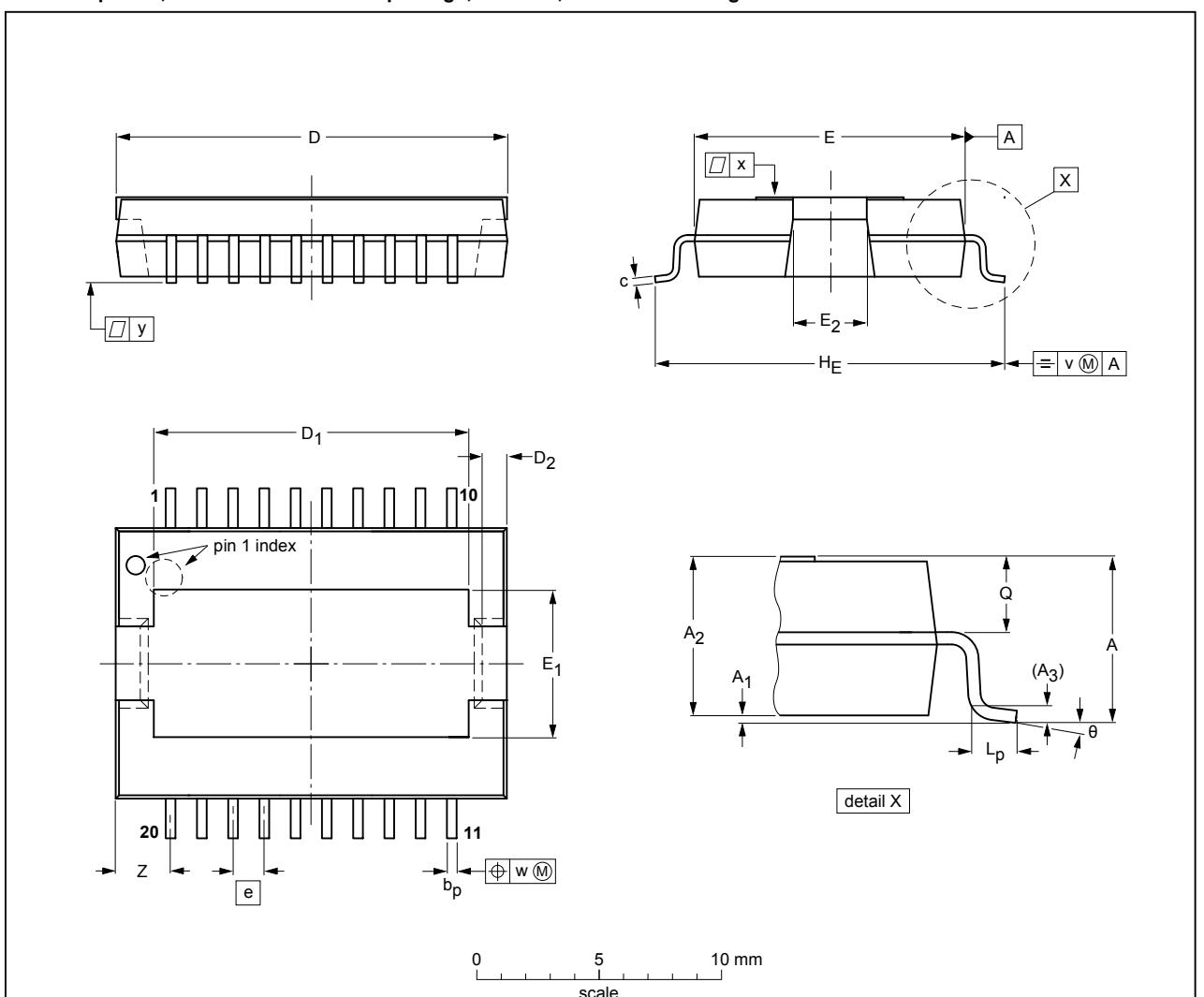
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	15.8	-	15.9	16	mm
E	package width	10.9	-	11	11.1	mm
A	seated height	[tbd]	-	3.5	3.5	mm
A <sub>2</sub>	package height	3.2	-	3.35	3.5	mm
n <sub>2</sub>	actual quantity of termination	-	-	20	-	



## 2. Package outline

HSOP20: plastic, heatsink small outline package; 20 leads; low stand-off height

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub> <sup>(1)</sup>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(2)</sup>	D <sub>1</sub>	D <sub>2</sub>	E <sup>(2)</sup>	E <sub>1</sub>	E <sub>2</sub>	e	H <sub>E</sub>	L <sub>p</sub>	Q	v	w	x	y	z	θ
mm	3.6	+0.10 -0.02	3.5 3.2	0.35 0.40	0.53 0.23	0.32 15.8	16.0 12.6	13.0 12.6	1.1 0.9	11.1 10.9	6.2 5.8	2.9 2.5	1.27	14.5 13.9	1.1 0.8	1.7 1.5	0.25 0.25	0.25 0.03	0.03 0.07	2.5 2.0	8° 0°	

## Notes

1. Limits per individual lead.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT418-4						-05-01-28-05-03-10

Fig. 1. Package outline HSOP20 (SOT418-4)

### 3. Legal information

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